



PCB Specification Datasheet

Date: 15-6-2009
Document: KS0002 V0.4
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Customer:

Contact:

Phone:

Email:

Date:

Document name:

Board type nr:

Board description:

Revision:

Article number:

Project:

Datacontainer:

Board details

Number of layers #

PCB Thickness mm

PCB Size x mm

Panel J/N

Max. Panel size x mm

Mechanical

V-scoring mm

Complex inner-rout J/N

Minimum hole size mm

Pressfit J/N

Blind via's J/N

Burried via's J/N

Materials

PCB base material

Finish

Finished Cu thickness μ

Soldermask top J/N

Soldermask bottom J/N

Silkscreem top J/N

Silkscreen bottom J/N

Peel-off top J/N

Peel-off bottom J/N

Via plugging top J/N

Via plugging bottom J/N

Lay-out details

Number of SMD sides 1 - 2

Minimum track μ

Minimum gap μ

Controlled Impedance J/N

Selective Goldplating J/N

Markings

UL-Logo J/N

Date code J/N

General

Documents attached J/N

Stencil info retour J/N

Electrical tested J/N

General remarks

HEAD Electronics BV

www.head.nl



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Lay-out details

Number of SMD sides 1 - 2
Minimum track μm
Minimum gap μm
Controlled Impedance J/N
Selective Goldplating J/N

Copperbalancing allowed in lay-out J/N
Copperbalancing allowed in break-off tabs J/N

General

Electrical test J/N
Stencil information retour J/N
Checkplots retour J/N
Stackup specified J/N
Documents attached J/N

Markings

UL logo J/N
Date code J/N
Pb-free logo J/N
Vendor logo J/N
Electrical test J/N

Email:
Email:

Warranty remarks

Packaging remarks

General remarks